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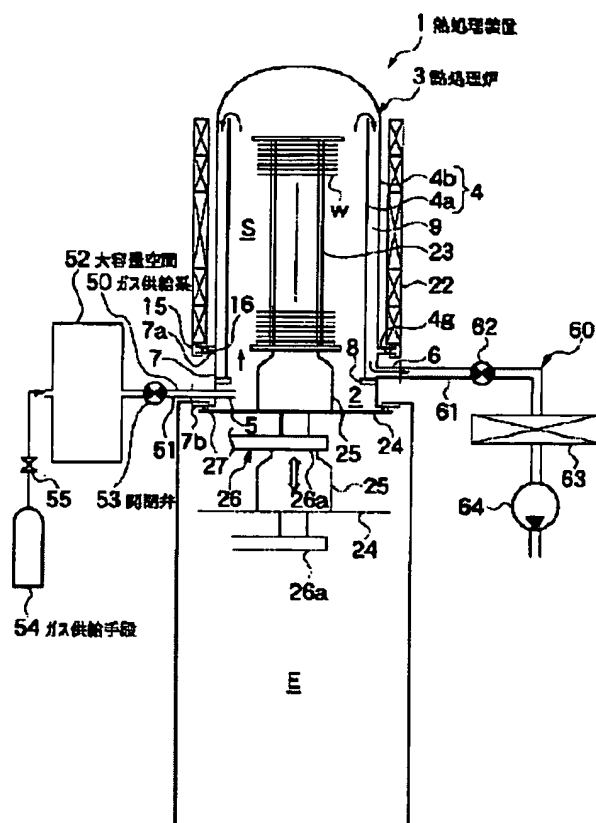
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APPLICANT : TOKYO ELECTRON LTD;

INVENTOR : TAMURA AKITAKE;

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TITLE : HEAT TREATING APPARATUS AND  
METHOD FOR CLEANING THE SAME



ABSTRACT : PROBLEM TO BE SOLVED: To improve productivity by enabling particles adhered in a heat treating furnace to be sufficiently removed and to enable heat treatment of proper quality, containing little particles to be executed.

SOLUTION: A heat treatment apparatus comprises a heat treatment furnace 3 for housing the material (w) to be treated to execute a predetermined heat treatment, a voltage volume space 52 provided in a gas supply system 50 for supplying gas into the furnace 3, an opening/closing valve 53 provided between the space 52 and the furnace 3, and a gas supply means 54 for supplying a cleaning gas in the furnace at a pressure higher than that in the furnace 3 into the space 52, to generate a pressure difference between the space 52 and the furnace 3. Thus, the valve 53 is opened to generate abrupt pressure change in the furnace for removing the particles adhered in the furnace 3.

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